

Abstract

The invention relates to packaging for microelectronic components (7) applied to a structure substrate (6) with the following:

- a carrier substrate (1) with a packaging receiving area (1v), at least predominantly an antiadhesion layer (2) being applied to the packaging receiving area (1v),
- a structure material (3') applied to the antiadhesion layer (2) with chamber openings (4) for accommodating the microelectronic components (7).

Furthermore this invention relates to a method for producing this packaging as well as a method for packaging and a method for detaching the carrier substrate.

Figure 5 in this regard